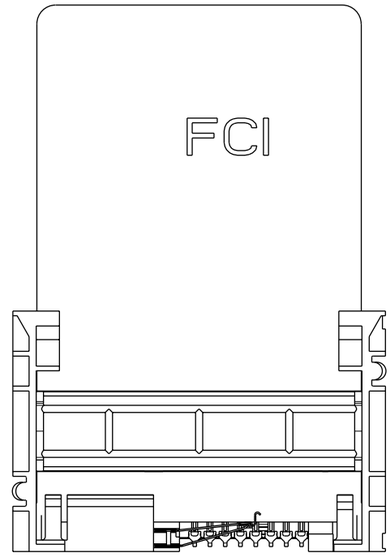
7334L2622F01LF

Catalogue Part Number Key

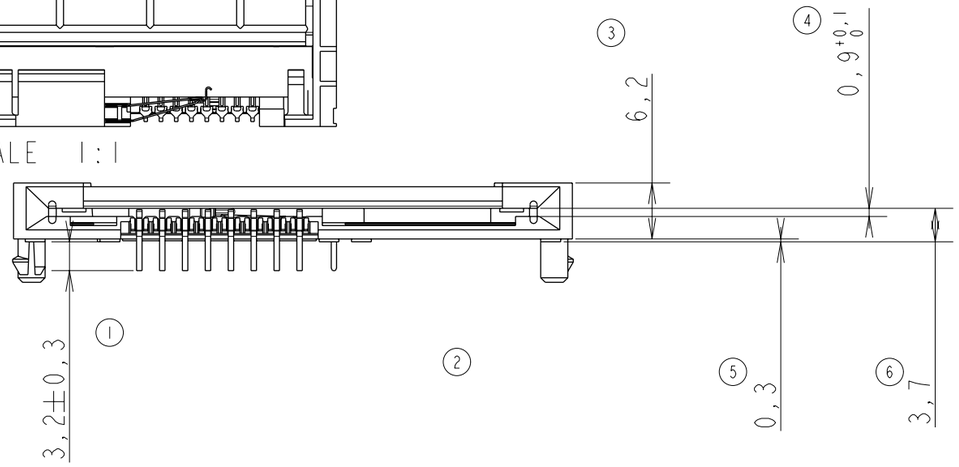
Lead Free Version (Optional)

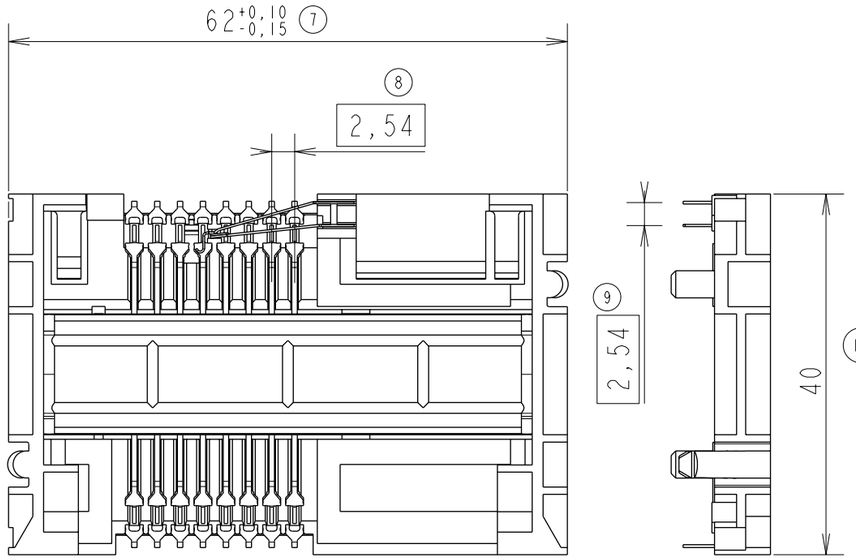
Durability
0: 2500 Mating Cycles
2: 10000 Mating Cycles
5: 100000 Mating Cycles

Number of contacts :
2: 8 contacts ISO
3: 16 contacts ISO + AFNOR



SCALE 1:1





ltr	ecn no	dr	date
A	F20307	DLE	2002/04/30
B	LS 3053	JTA	2003/05/13
C	105-0071	DTK	2005/06/25
D	106-0084	SSC	2006/06/21
E	106-0183	SSC	2006/10/05
F	109-0002	SSC	2009/01/02
-	-	-	-

GENERAL:
This L26 connector uses a "sliding" contact technology suitable for most applications.
It has been designed for easy mounting on the PCB.

ELECTRICAL PROPERTIES:
Insulation resistance : 5000 MΩ min
Dielectric withstanding : 750 Vrms min
Current carrying capacity : 10µA min. 1A max
Contact resistance : 100mΩ max
Card sensor type : Normally closed

MECHANICAL PROPERTIES:
Contact Normal force : 0.6 N max (EMV Standard)
Insertion force : 10 N max
Extraction force : 1 N min
Durability : 10000 card insertions with 0.4µm Gold
According to UTE C93-421

SWITCH:
Contact Closed Resistance: 100mΩ Max
Open Contact Voltage Proof: 250 Vrms Min

MATERIAL:
Housing : Thermoplastic 30 % Glass Filled, Colour Black, Rated UL94V0
Contacts and switch : Phosphor bronze
Plating : Nickel all over with 3µm mini on contact area
Gold over Nickel on contact area
Tin/Lead 3 µm mini on soldertails
FOR LEAD FREE PLATING :
Matte Tin 3µm mini on solder tail in place of Tin/Lead
Bare edge allowed

ENVIRONMENT:
Operating temperature: -40°C / +85°C
Storage temperature: -40°C / +85°C
Printed Circuit Board thickness : 1.6mm

REFERENCE DOCUMENTS:
Product specification VGN 11596
Packaging Specification VGN 11619

LEAD FREE VERSION:

"This product meets European Union Directives and other country regulations as described in GS-22-008"

The housing will withstand exposure to 260°C peak temperature for 10seconds in a wave solder application with a 1.6mm minimum thick circuit board.
Use protective adhesive tape (Kapton orTeflon) or protective metallic devices on the areas which are directly exposed to wave soldering as it is used in classical leaded wave soldering

General Tolerances: ± 0.2 mm

www.fciconnect.com			surface - ISO 1302		tolerance std ISO 406 ISO 1101		projection	mm
			TOLERANCES UNLESS OTHERWISE SPECIFIED					
Dr	N.TWINCY	2002/04/30	ANGULAR	LINEAR	0.X	±	size A3	Scale 3:2
Eng	F TISSERAND	2002/04/30			0.XX	±		
Chr	S.S.CHERIAN	2009/01/02	0° ±		0.XXX	±	ECN	109-0002
Appr	S.S.CHERIAN	2009/01/02	Product family			5S2F	Spec ref	SEE NOTES

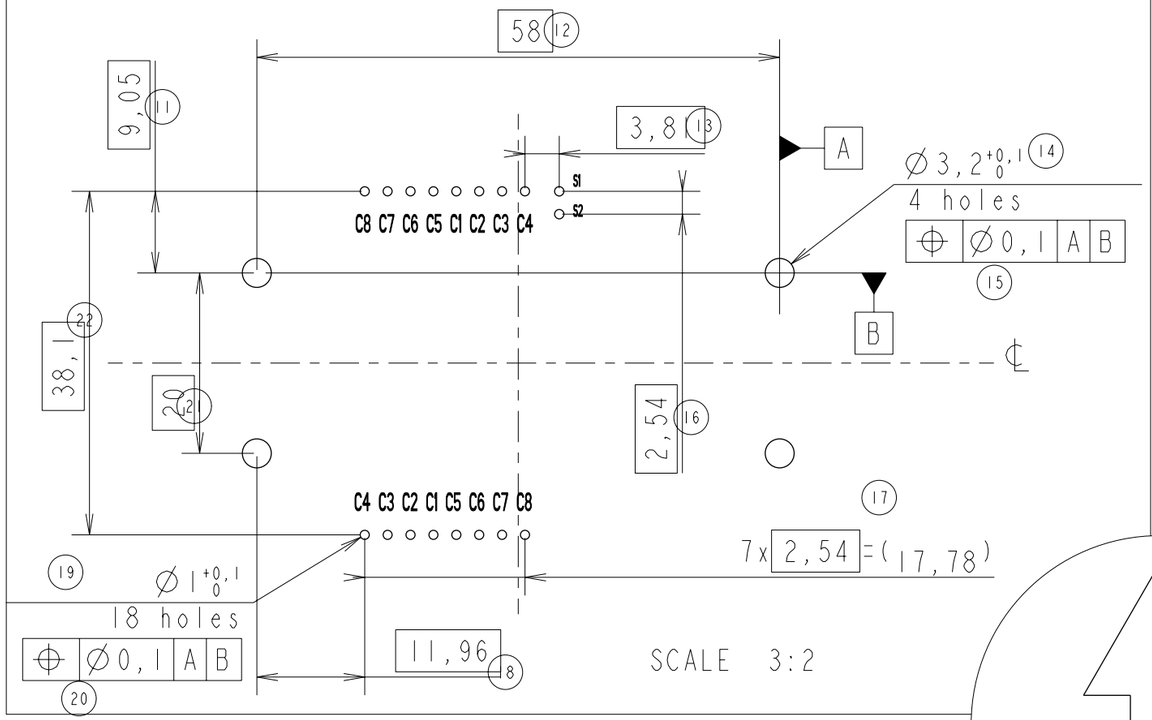
title	L26 TYPE F01 --	dwg no	VJW_54701 Rev. F
catalog no	SEE TABLE	-	sheet 1 of 2

REV F - 2006-04-17

PDM: Rev:F STATUS:Released Printed: Jan 11, 2009

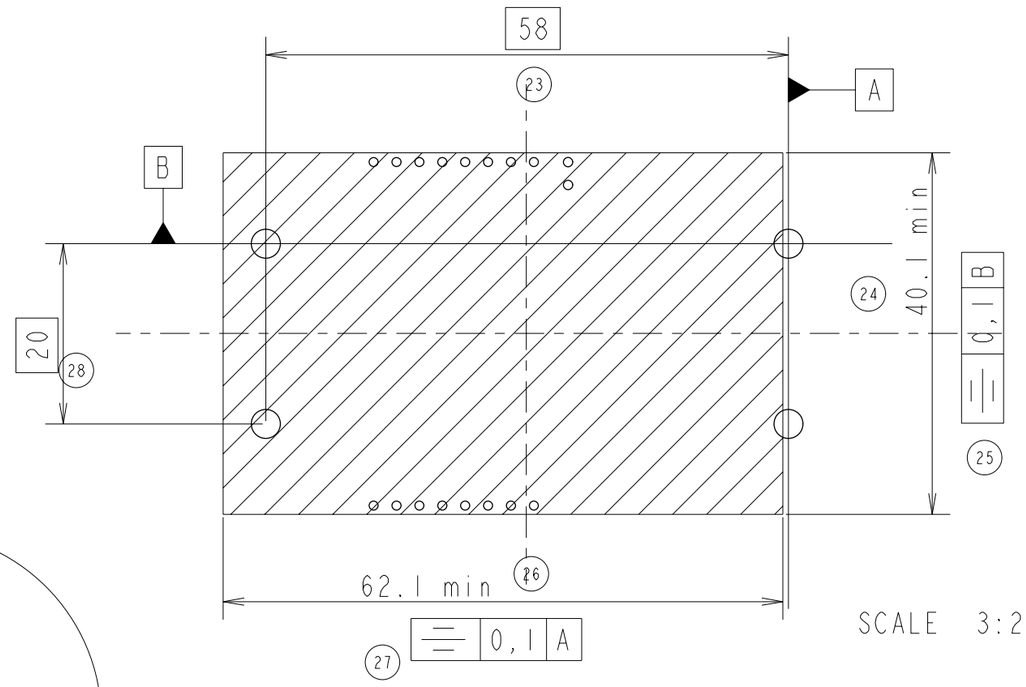
RECOMMENDED PCB LAYOUT

CONTACT CONFIGURATION : ISO & AFNOR
(CONNECTOR SIDE)



SCALE 3:2

STANDARD LAYOUT FOR 'KEEP OUT ZONE' (Connector Side)



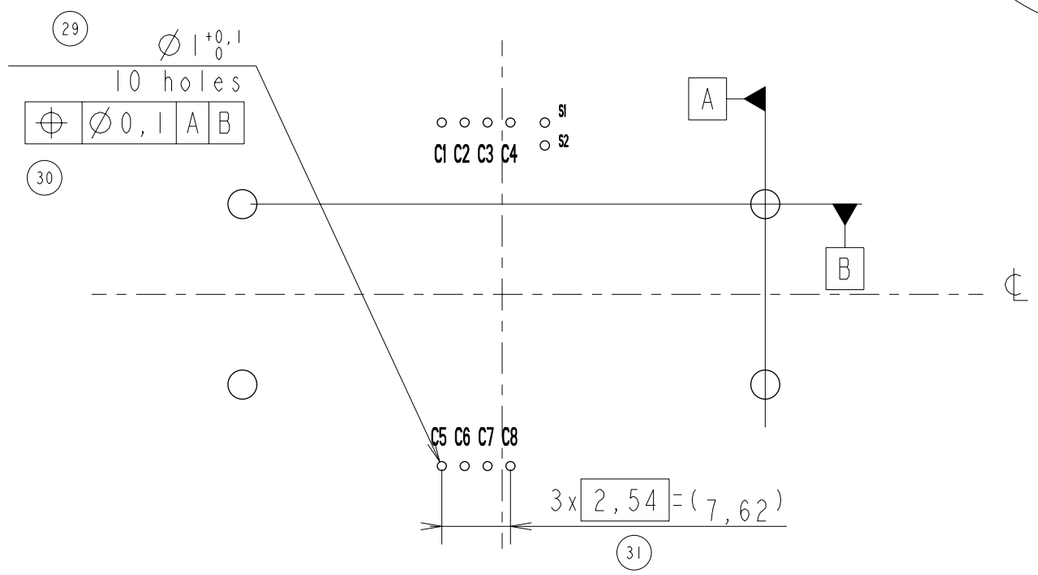
SCALE 3:2

Hatching area might be free of components

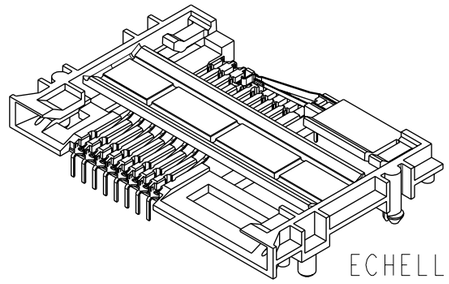
CARD INSERTION

RECOMMENDED PCB LAYOUT

CONTACT CONFIGURATION : ISO
(CONNECTOR SIDE)



SCALE 3:2



ECHELLE 1:1

EUROPEAN PROJECTION

www.fciconnect.com			surface ISO 1302		tolerance std ISO 406 ISO 1101		projection	mm
			TOLERANCES UNLESS OTHERWISE SPECIFIED					
Dr	N.TWINCY	2002/04/30	ANGULAR	LINEAR	0.X	±	size A3	Scale 3:2
Eng	F TISSERAND	2002/04/30			0.XX	±		
Chr	S.S.CHERIAN	2009/01/02	0° ±°		0.XXX	±	ECN	109-0002
Appr	S.S.CHERIAN	2009/01/02	Product family			5S2F	Spec ref	SEE NOTES
	title: L26 TYPE F01 --				dwg no: VJW_54701			Rev. F
	catalog no: SEE TABLE				-			sheet 2 of 2